



SLOVENSKI STANDARD
oSIST prEN IEC 62878-2-603:2023
01-december-2023

Tehnologija sestavov z vdelanimi elementi - 2-603. del: Smernice za zložene elektronske module - Preskusna metoda vmesnih modulov električne povezljivosti

Device embedding assembly technology - Part 2-603: Guideline for stacked electronic module - Test method of intra-module electrical connectivity

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ICS:

- | | | |
|--------|---------------------------------------|---------------------------------|
| 31.180 | Tiskana vezja (TIV) in tiskane plošče | Printed circuits and boards |
| 31.190 | Sestavljeni elektronski elementi | Electronic component assemblies |

oSIST prEN IEC 62878-2-603:2023 **en**



91/1901/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

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SECRETARIAT: Japan	SECRETARY: Mr Osamu IKEDA
OF INTEREST TO THE FOLLOWING COMMITTEES:	PROPOSED HORIZONTAL STANDARD: <input type="checkbox"/> Other TC/SCs are requested to indicate their interest, if any, in this CDV to the secretary.
FUNCTIONS CONCERNED: <input checked="" type="checkbox"/> EMC <input type="checkbox"/> ENVIRONMENT <input type="checkbox"/> QUALITY ASSURANCE <input type="checkbox"/> SAFETY	
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TITLE:

Device embedding assembly technology - Part 2-603: Guideline for stacked electronic module - Test method of intra-module electrical connectivity

PROPOSED STABILITY DATE: 2024

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

DEVICE EMBEDDING ASSEMBLY TECHNOLOGY
**Part 2-603: Guideline for stacked electronic module –
Test method of intra-module electrical connectivity**

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The text of International Standard is based on the following documents:

Draft	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at

81 www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in
82 greater detail at www.iec.ch/standardsdev/publications.

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- 86 • reconfirmed,
- 87 • withdrawn,
- 88 • replaced by a revised edition, or
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